

IN THE SPECIFICATION:

Please amend paragraph [0023] as follows:

[0023] The amount of adhesive material that is introduced between the first and second semiconductor devices spaces the first and second semiconductor devices a distance substantially the same as a predetermined distance apart from one another. Various criteria, such as the viscosity of the adhesive material, the surface tension of the adhesive material, shrinkage or expansion of the adhesive material upon curing, the surface area to which the adhesive material is applied, the weight of the second semiconductor device, the force applied to the second semiconductor die upon placement thereof, or discrete conductive elements positioned between the first and second semiconductor ~~die,~~ devices, may factor into the predetermined distance that may be achieved with a particular volume of a specific type of adhesive material.